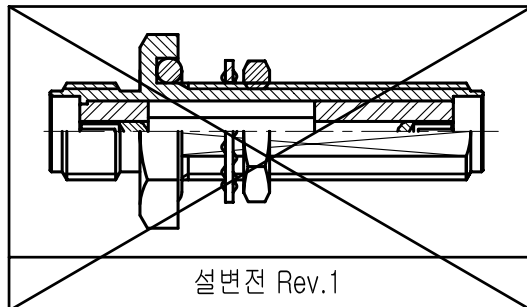
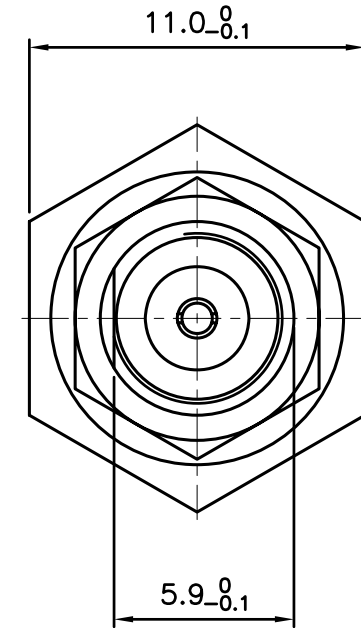
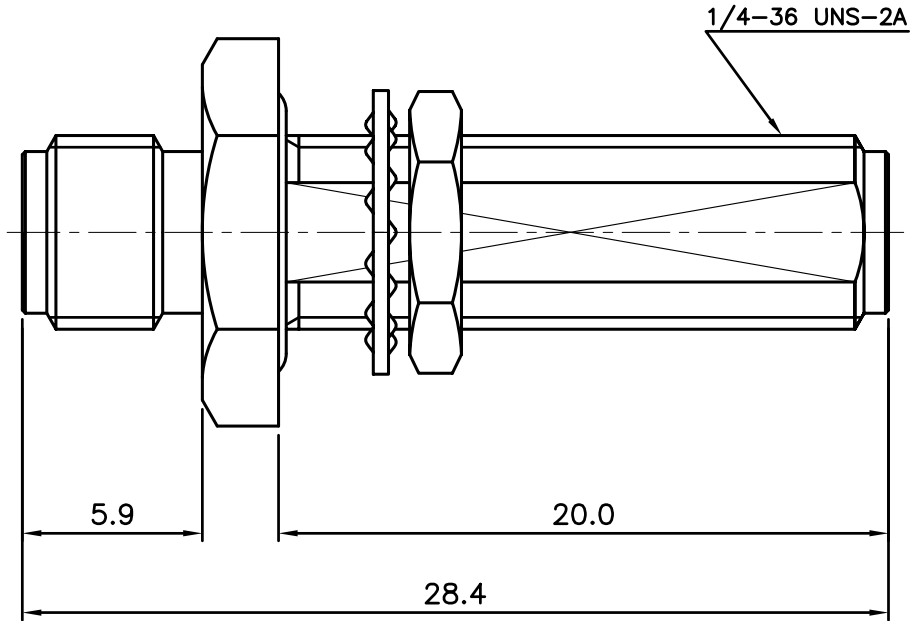


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration			2006.12.16.
1	초립성 개선 [설변No.연구2007-031] (코킹 위치 변경- 내부 TEF+PIN 방향 변경)	E.H.KIM	S.J.YOUN	2007.02.02.
2	바디 내부 뉘시바를 추가	I.C.KIM		2020.06.25.



6	WASHER	1	BsS	Gold Plate	DWA00005-5/1
5	NUT	1	MBsBD C3604BD-F	Gold Plate	DNT00025-5/1
4	INSULATOR	2	TEFLON		DIN02817-N/1
3	GASKET	1	SILICONE RUB		DGK00023-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT01315-5/2 DCT01315-5/1
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD01689-5/2 DBD01689-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2020. 06. 25.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY		
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMA50 (J) SMA50 (J) BH ADAPTOR
		DRAWN BY	I.C.KIM	
FINISH		SCALE	UNIT	A4 DWG NO. AD00182-7/1 REVISION 2 SHEET 1 of 1
		4/1	mm	